

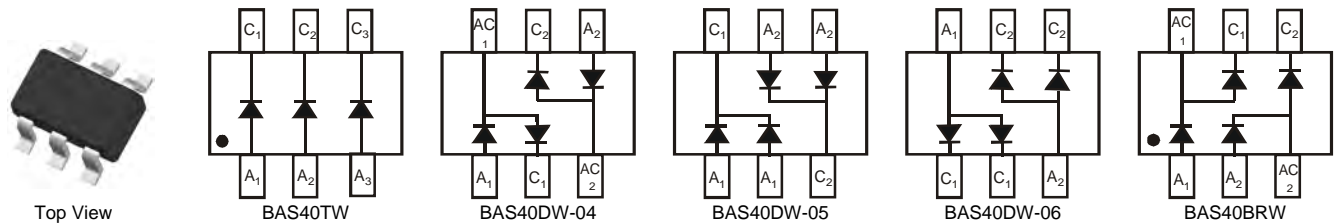
SURFACE MOUNT SCHOTTKY BARRIER DIODE ARRAYS

Features

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- **Lead Free/RoHS Compliant (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **"Green" Device (Notes 4 and 5)**

Mechanical Data

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Polarity: See Diagrams Below
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)



Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{R(RM)}	40	V
Working Peak Reverse Voltage	V _{R(WM)}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	28	V
Forward Continuous Current (Note 1)	I _{FM}	200	mA
Non-Repetitive Peak Forward Surge Current @ t < 1.0s	I _{FSM}	600	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P _D	200	mW
Thermal Resistance Junction to Ambient Air (Note 1)	R _{θJA}	625	°C/W
Operating Temperature Range	T _J	-55 to +125	°C
Storage Temperature Range	T _{STG}	-65 to +125	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	V _{(BR)R}	40	—	V	I _R = 10μA
Forward Voltage	V _F	—	380	mV	I _F = 1.0mA, t _p < 300μs
			1000	mV	I _F = 40mA, t _p < 300μs
Reverse Current (Note 2)	I _R	—	200	nA	V _R = 30V
Total Capacitance	C _T	—	5.0	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{rr}	—	5.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 x I _R , R _L = 100Ω

- Notes:
1. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 2. Short duration pulse test used to minimize self-heating effect.
 3. No purposefully added lead.
 4. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants

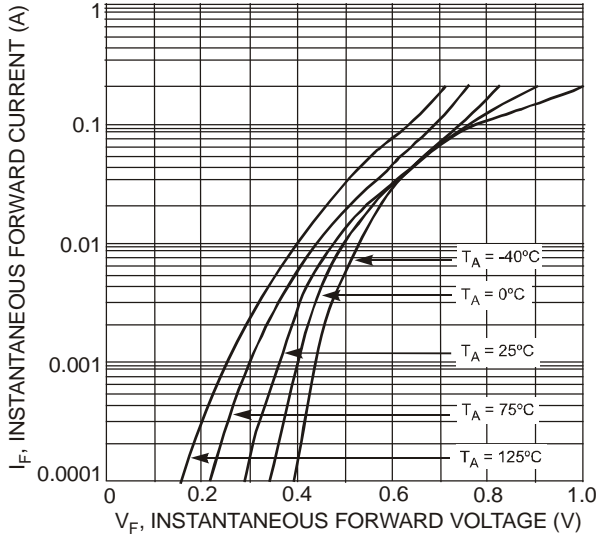


Fig. 1 Typical Forward Characteristics

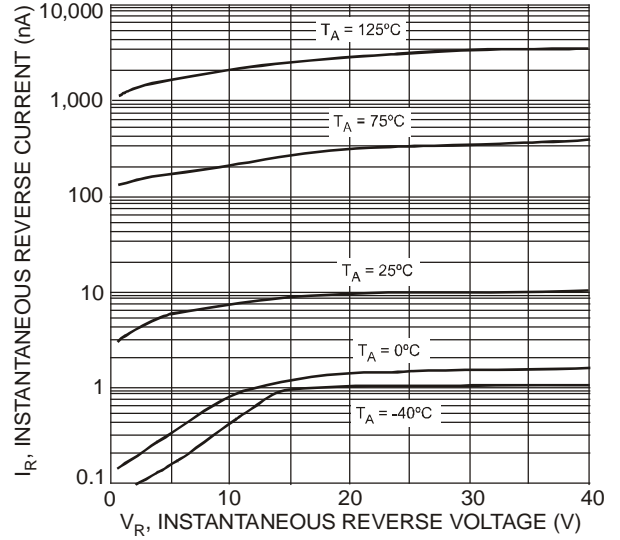


Fig. 2 Typical Reverse Characteristics

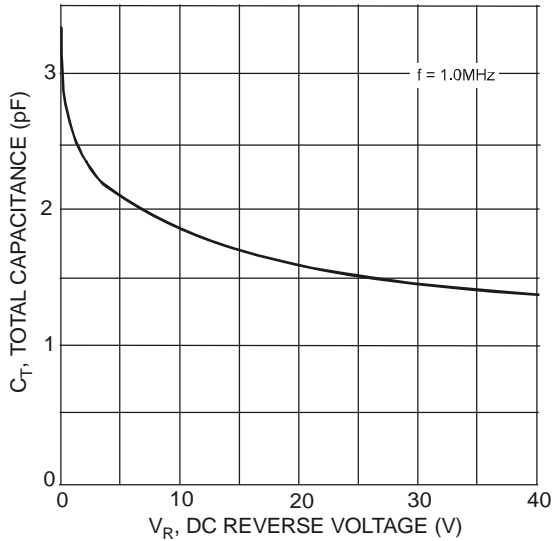


Fig. 3 Total Capacitance vs. Reverse Voltage

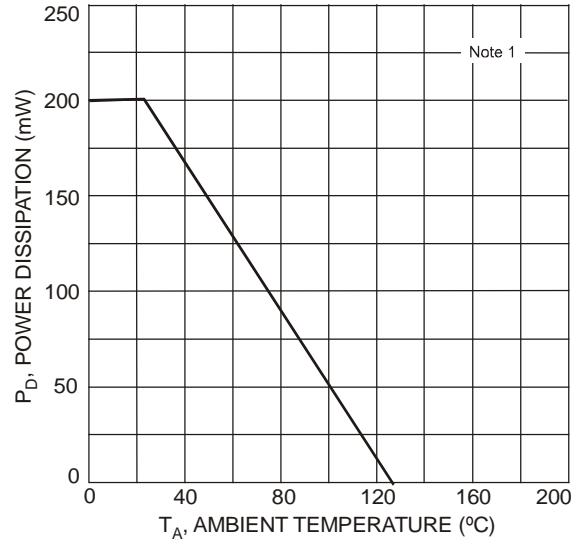


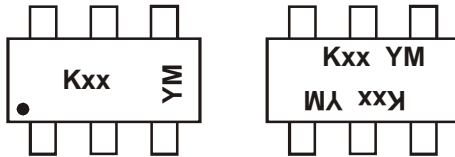
Fig. 4 Power Derating Curve, Total Package

Ordering Information (Note 6)

Part Number	Case	Packaging
BAS40TW-7-F	SOT-363	3000/Tape & Reel
BAS40DW-04-7-F	SOT-363	3000/Tape & Reel
BAS40DW-05-7-F	SOT-363	3000/Tape & Reel
BAS40DW-06-7-F	SOT-363	3000/Tape & Reel
BAS40BRW-7-F	SOT-363	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



Kxx = Product Type Marking Code

- K43 = BAS40TW
- K44 = BAS40DW-04
- K45 = BAS40DW-05
- K46 = BAS40DW-06
- K47 = BAS40BRW

For Assymetrical Configuration, orientation indicator as shown

For Symmetrical Configuration, no orientation indicator

YM = Date Code Marking

Y = Year (ex: N = 2002)

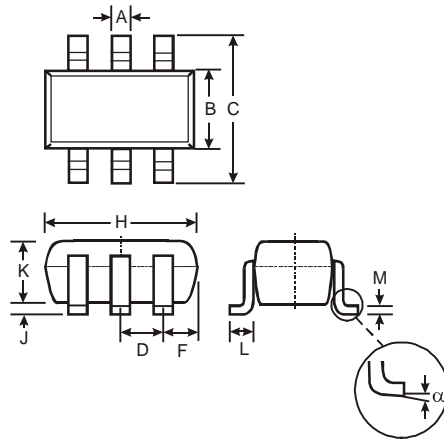
M = Month (ex: 9 = September)

Date Code Key

Year	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	L	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C

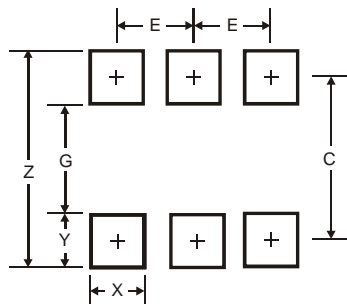
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Nominal	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C	1.9
E	0.65

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